



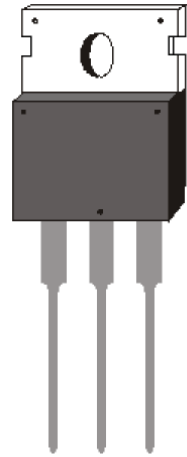
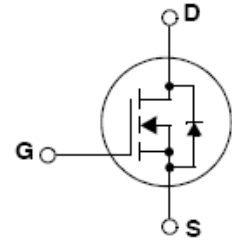
BYD Microelectronics Co., Ltd.

BF90880SNL

80V N-Channel MOSFET

General Description

This Power MOSFET device has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any application with low gate drive requirement.



TO220

Features

- $V_{DS} = 80\text{ V}$
- $I_D = 80\text{ A}$
- Typical $R_{DS(ON)} = 8\text{ m}\Omega$ ($V_{GS} = 10\text{ V}, I_D = 40\text{ A}$)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	80	V
I_D	Drain Current(continuous)at $T_c = 25^\circ\text{C}$	80	A
I_{DM}	Drain Current (pulsed) (Note1)	320	A
V_{GS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (Note2)	1200	mJ
I_{AR}	Avalanche Current (Note1)	33	A
P_D	Power Dissipation ($T_c = 25^\circ\text{C}$)	178	W
T_J, T_{stg}	Operating junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose	300	$^\circ\text{C}$



Ordering Information

Part Number	Package	Packaging
BF90880SNL	TO-220	Tube

Thermal Data

Symbol	Parameter	Max.	Unit
Rthj-Case	Thermal Resistance Junction-Case	0.7	°C/W
Rthj-Amb	Thermal Resistance Junction-Ambient	62	°C/W

Electrical Characteristics($T_c = 25^\circ\text{C}$)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	80			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_c=25^\circ\text{C}$			1	μA
		$V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_c=125^\circ\text{C}$			10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	2.0		4.0	V
$R_{DS(on)}$	Static Drain-Source On Resistance	$V_{GS}=10\text{V}$, $I_D=40\text{A}$		8	10	m Ω
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $f=1\text{MHz}$, $V_{GS}=0\text{V}$		4575		pF
C_{oss}	Output Capacitance			376		pF
C_{rss}	Reverse Transfer Capacitance			41		pF
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=40\text{V}$, $I_D=30\text{A}$ $V_{GS}=10\text{V}$, $R_G=4.7\Omega$ (Note3, 4)		36		ns
t_r	Rise Time			35.8		ns
$t_{d(off)}$	Turn-Off Delay Time			99.4		ns
t_f	Fall Time			31.5		ns
Q_g	Total Gate Charge	$V_{DS}=64\text{V}$, $I_D=80\text{A}$ $V_{GS}=4.5\text{V}$ (Note3, 4)		110		nC
Q_{gs}	Gate-Source Charge			16		nC
Q_{gd}	Gate-Drain Charge			40		nC
$V_{SD(*)}$	Forward On Voltage	$I_{SD}=80\text{A}$, $V_{GS}=0\text{V}$			1.5	V
T_{rr}	Reverse Recovery Time	$V_{DD}=30\text{V}$, $I_F=80\text{A}$, $di/dt=100\text{A}/\mu\text{s}$ (Note3)		120		ns

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
 2. $V_{DD} = 40\text{V}$, $L = 2\text{mH}$, Starting $T_J = 25^\circ\text{C}$
 3. Pulse Test : Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
 4. Essentially independent of operating temperature
- (*) Pulsed: Pulse duration

Typical characteristics (25°C unless noted)

Figure 1 Output Characteristics

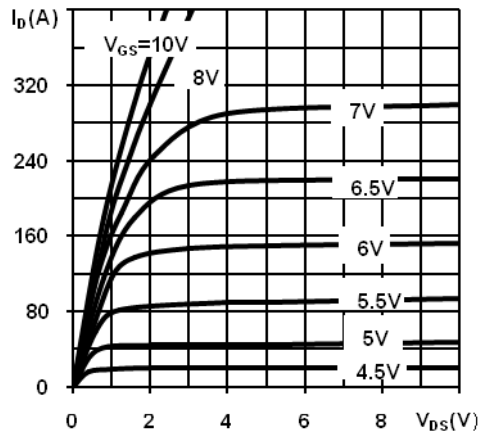


Figure 2 Transfer Characteristics

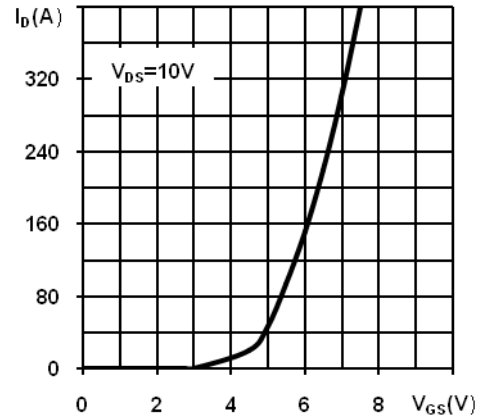


Figure 3 Normalized Threshold Voltage Vs. Temperature

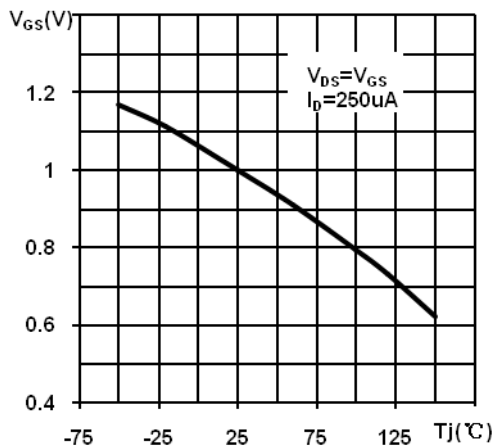


Figure 4 Normalized BV_{DSS} Vs. Temperature

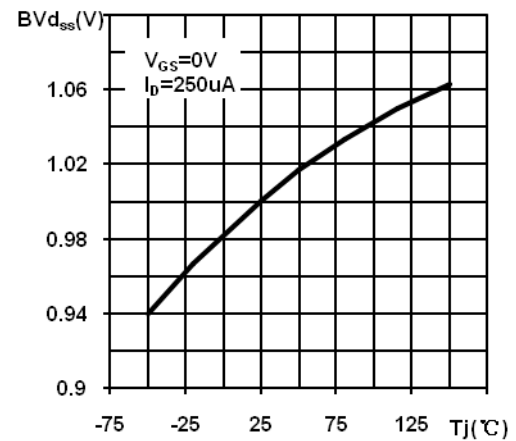


Figure 5 Normalized on Resistance Vs. Temperature

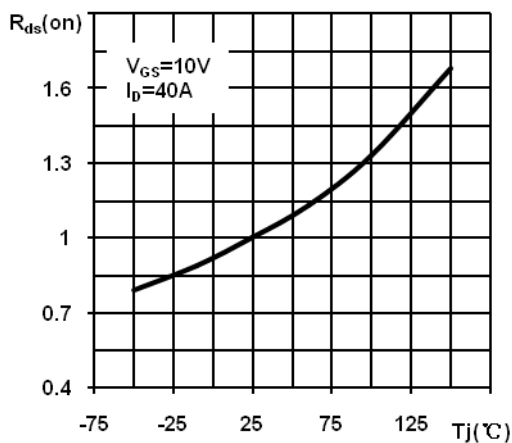


Figure 6 Source-Drain Diode Forward Characteristics

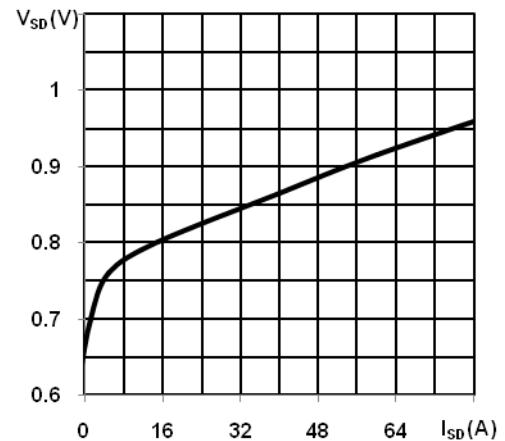


Figure 7 Capacitance

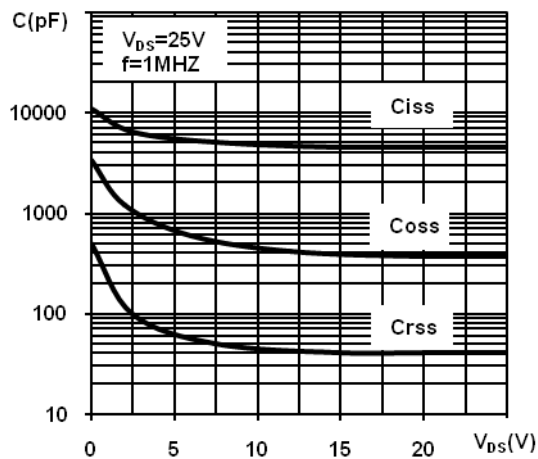


Figure 8 Gate Charge

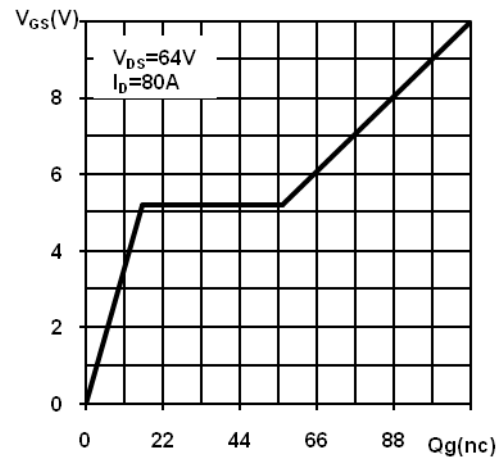


Figure 9 Safe Operating Area

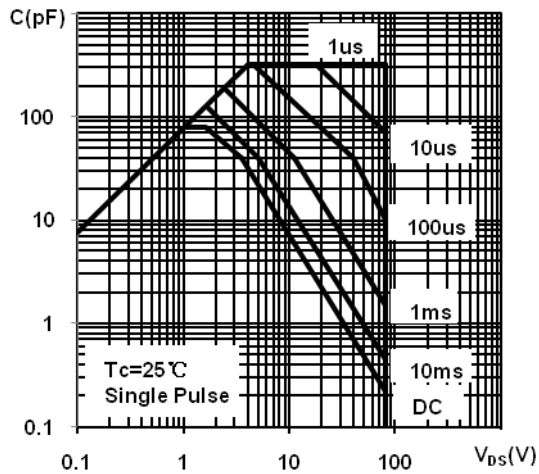


Figure 10 Maximum Drain Current Vs. Case Temperature

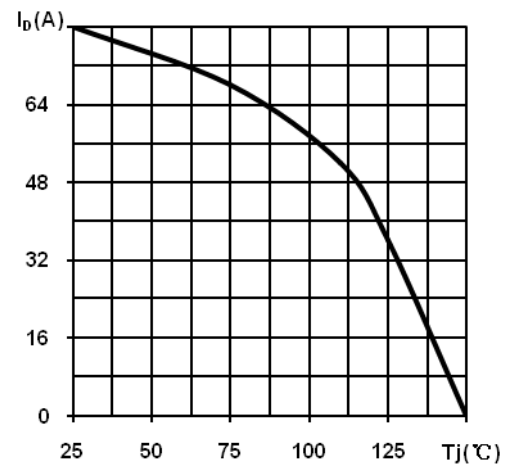
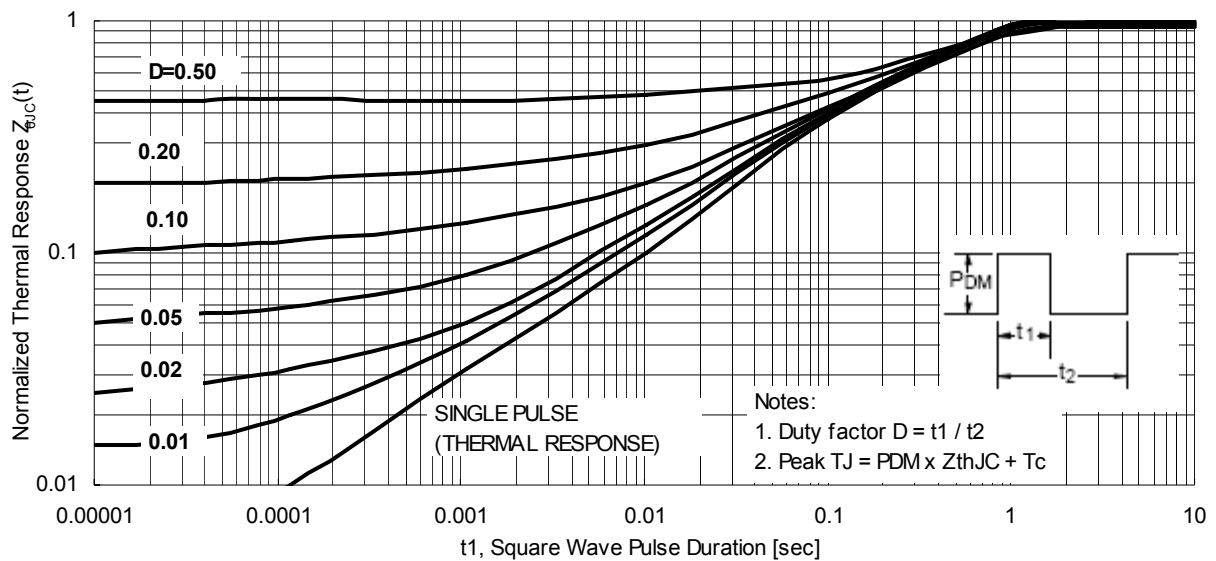
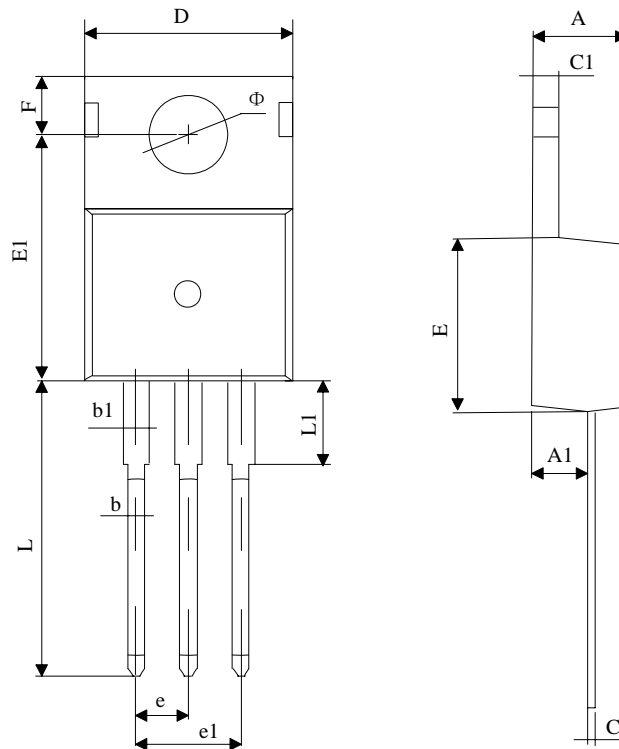


Figure 11 Normalized Maximum Transient Thermal Impedance



Package Drawing



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.45	4.55	0.175	0.179
A1	2.38	2.42	0.093	0.095
b	0.70	0.90	0.028	0.035
b1	1.42	1.62	0.056	0.064
c	0.45	0.55	0.018	0.022
c1	1.25	1.35	0.049	0.053
D	9.85	9.95	0.388	0.392
E	9.11	9.29	0.359	0.366
E1	12.85	12.95	0.506	0.510
e	2.540TYP		0.100TYP	
e1	5.04	5.12	0.198	0.202
F	2.77	2.83	0.109	0.111
L	12.98	13.18	0.511	0.519
L1	2.97	3.03	0.117	0.119
Φ	3.58	3.62	0.141	0.143



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